"Advancing the Science of Semiconductor Manufacturing Excellence"

ASMC 2003 PROCEEDINGS

The IEEE/SEMI Advanced Semiconductor Manufacturing Conference and Workshop is an annual forum that provides a venue for the presentation of methodologies, approaches and techniques required to achieve world-class semiconductor manufacturing. A key role this conference plays is in promoting interaction among semiconductor professionals at all levels. The goal and objective of the conference are to assist in making the participating companies more knowledgeable of semiconductor production methods, encourage open communication between participants, and develop the strategic relationship between users and suppliers needed to achieve manufacturing excellence and improve global competitiveness.

31 March – 1 April, 2003
Munich, Germany
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- International Electron Devices Meeting (IEDM)
- International Symposium on Semiconductor Manufacturing (ISSM)
- Intersociety Conference on Thermal Phenomena in Electronic Systems (I-THERM)
- Electronic Components & Technology Conference (ECTC)
- International Electronic Manufacturing Technology (IEMT) Symposium

Copies of past proceedings of some of these conferences are available for purchase. In addition, EDS and CPMTs publish the Transactions on Semiconductor Manufacturing, the archival journal in this field. We invite you to consider membership for one of the IEEE Societies and to participate with us in furthering advancements in these fields. If you already belong to another professional society, you can affiliate with EDS or CPMT at reduced fees. Please refer to the back cover for additional information.

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Paul Werbaneth, Tegal Corp.
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Holger Vogt, Kohnholt Institute of Microelecroniic Circuits and Systems

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Deliev Glion, AMD Saxony LLC & Co. KG

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L. Date, D. Pique, L. van-Auvert, Applied Materials; S. Van Elshocht, M. Ceylan, IMEC; Z.M. Ritterma, D. Massoudre, Y. Postmarov, F. Rozengrub, Philips Research

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BIOGRAPHIES OF SPEAKERS

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